SC-SMT 3.81/07/135G 3.2SN BK BX

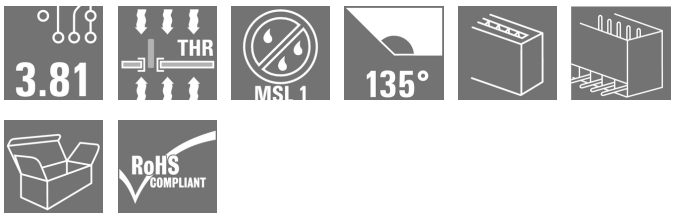
Weidmüller Interface GmbH & Co. KG
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Product image



similar to Illustration



The high-temperature-resistant SC-SMT pin header with 135° wire outlet direction: the 135° angle exists between the plugging direction and the solder pin. The wire outlet direction is then diagonal or 45° to the PCB.

- More freedom when designing components and devices.
- Easy access and a high component density when multiple interfaces are arranged in parallel within a single plugging area
- The housing design is application-friendly because of the additional optional wire outlet direction.
- Available as closed (G) and with solder flange (LF).
- Pin length of either 1.5 mm or 3.2 mm

Weidmüller's 3.81-mm-pitch (0.15 inch) plug-in connectors are compatible with the layouts of standard connectors and offer space for labelling and coding.

General ordering data

Version	PCB plug-in connector, male header, closed side, THT/THR solder connection, 3.81 mm, Number of poles: 7, 135°, Solder pin length (l): 3.2 mm, tinned, black, Box
Order No.	1977250000
Type	SC-SMT 3.81/07/135G 3.2SN BK BX
GTIN (EAN)	4032248685264
Qty.	50 pc(s).
Product data	IEC: 320 V / 17.5 A UL: 300 V / 11 A
Packaging	Box

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Technical data

Dimensions and weights

Depth	13.1 mm	Depth (inches)	0.516 inch
Height	14.2 mm	Height (inches)	0.559 inch
Height of lowest version	11 mm	Width	28.06 mm
Width (inches)	1.105 inch	Net weight	3.5 g

System specifications

Product family	OMNIMATE Signal - series BC/SC 3.81	Type of connection	Board connection
Mounting onto the PCB	THT/THR solder connection	Pitch in mm (P)	3.81 mm
Pitch in inches (P)	0.15 inch	Outgoing elbow	135°
Number of poles	7	Number of solder pins per pole	1
Solder pin length (l)	3.2 mm	Solder pin length tolerance	0 / -0,02 mm
Solder pin dimensions	d = 1.0 mm, Octagonal	Solder pin dimensions = d tolerance	0 / -0,03 mm
Solder eyelet hole diameter (D)	1.3 mm	Solder eyelet hole diameter tolerance (D)	+ 0,1 mm
Outside diameter of solder pad	2.1 mm	Template aperture diameter	1.9 mm
L1 in mm	22.86 mm	L1 in inches	0.9 inch
Number of rows	1	Pin series quantity	1
Touch-safe protection acc. to DIN VDE 57 106	Safe from finger touch	Touch-safe protection acc. to DIN VDE 0470	IP 20
Volume resistance	≤5 mΩ	Can be coded	Yes

Material data

Insulating material	LCP GF	Colour	black
Colour chart (similar)	RAL 9011	Insulating material group	IIIa
Comparative Tracking Index (CTI)	≥ 175	Moisture Level (MSL)	1
UL 94 flammability rating	V-0	Contact material	Copper alloy
Contact surface	tinned	Storage temperature, min.	-40 °C
Storage temperature, max.	70 °C	Operating temperature, min.	-50 °C
Operating temperature, max.	120 °C	Temperature range, installation, min.	-25 °C
Temperature range, installation, max.	120 °C		

Rated data acc. to IEC

tested acc. to standard	IEC 60664-1, IEC 61984	Rated current, min. number of poles (Tu=20°C)	17.5 A
Rated current, max. number of poles (Tu=20°C)	17.1 A	Rated current, min. number of poles (Tu=40°C)	17.5 A
Rated current, max. number of poles (Tu=40°C)	17.5 A	Rated voltage for surge voltage class / pollution degree II/2	320 V
Rated voltage for surge voltage class / pollution degree III/2	160 V	Rated voltage for surge voltage class / pollution degree III/3	160 V
Rated impulse voltage for surge voltage class/ pollution degree II/2	2.5 kV	Rated impulse voltage for surge voltage class/ pollution degree III/2	2.5 kV
Rated impulse voltage for surge voltage class/ contamination degree III/3	2.5 kV	Short-time withstand current resistance	3 x 1s with 76 A

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Technical data

Rated data acc. to CSA

Institute (CSA)		Certificate No. (CSA)	200039-1121690
Rated voltage (Use group B / CSA)	300 V	Rated current (Use group B / CSA)	11 A
Reference to approval values	Specifications are maximum values, details - see approval certificate.		

Packing

Packaging	Box	VPE length	102 mm
VPE width	72 mm	VPE height	48 mm

Classifications

ETIM 6.0	EC002637	ETIM 7.0	EC002637
ETIM 8.0	EC002637	ECLASS 9.0	27-44-04-02
ECLASS 9.1	27-44-04-02	ECLASS 10.0	27-44-04-02
ECLASS 11.0	27-46-02-01	ECLASS 12.0	27-46-02-01

Important note

IPC conformity	Conformity: The products are developed, manufactured and delivered according international recognized standards and norms and comply with the assured properties in the data sheet resp. fulfill decorative properties in accordance with IPC-A-610 "Class 2". Further claims on the products can be evaluated on request.
Notes	• Rated current related to rated cross-section & min. No. of poles. • Rated data refer only to the component itself. Clearance and creepage distances to other components are to be designed in accordance with the relevant application standards. • P on drawing = pitch • Long term storage of the product with average temperature of 50 °C and average humidity 70%, 36 months

Approvals

Approvals	
ROHS	Conform
UL File Number Search	UL Website
Certificate No. (cURus)	E60693

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Technical data

Downloads

Approval/Certificate/Document of Conformity	Declaration of the Manufacturer
Engineering Data	CAD data – STEP
Catalogues	Catalogues in PDF-format
Brochures	FL DRIVES EN MB SMT EN FL DRIVES DE MB DEVICE MANUF. EN FL BUILDING SAFETY EN FL APPL LED LIGHTING EN FL INDUSTR.CONTROLS EN FL MACHINE SAFETY EN FL HEATING ELECTR EN FL APPL_INVERTER EN FL_BASE_STATION_EN FL ELEVATOR EN FL POWER SUPPLY EN FL 72H SAMPLE SER EN PO OMNIMATE EN PO OMNIMATE EN
White paper surface mount technology	Download Whitepaper

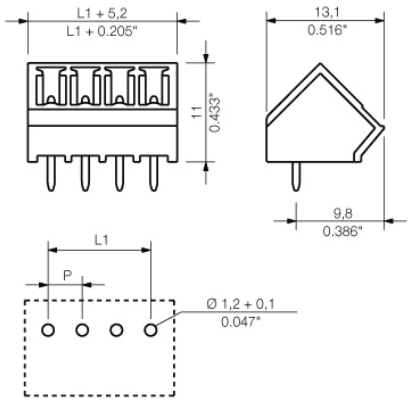
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Drawings

Dimensional drawing

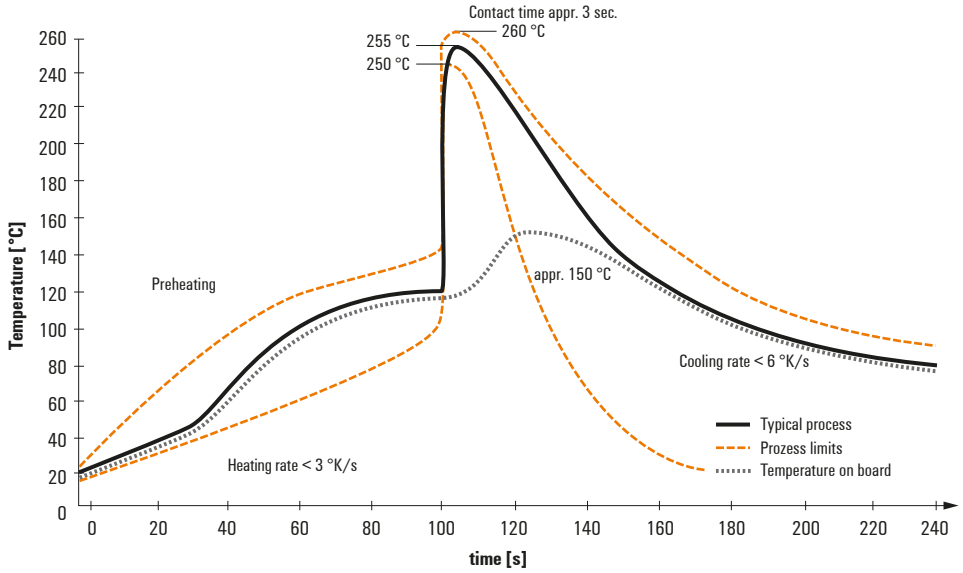


Wave Solder Profile

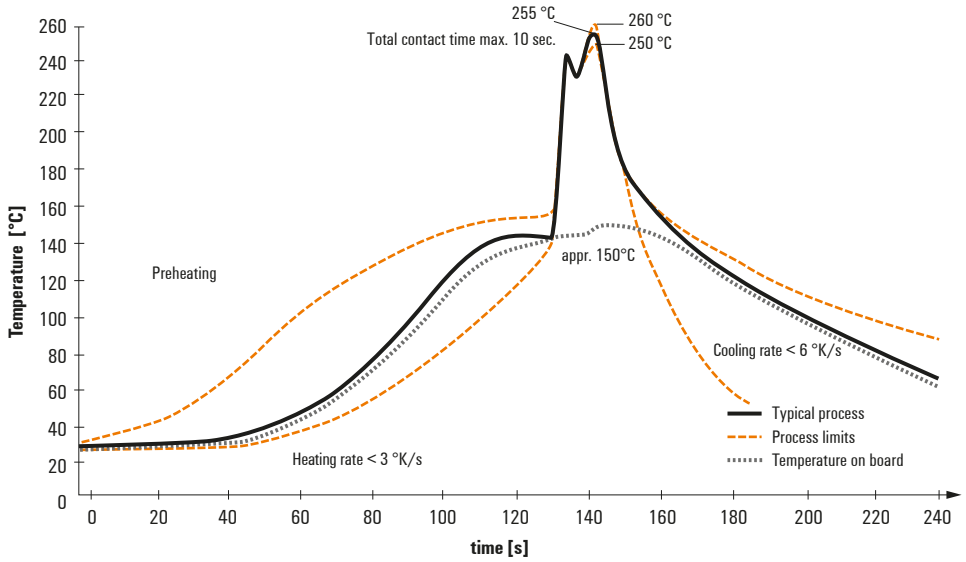
Recommended wave solderding profiles

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Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:
- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

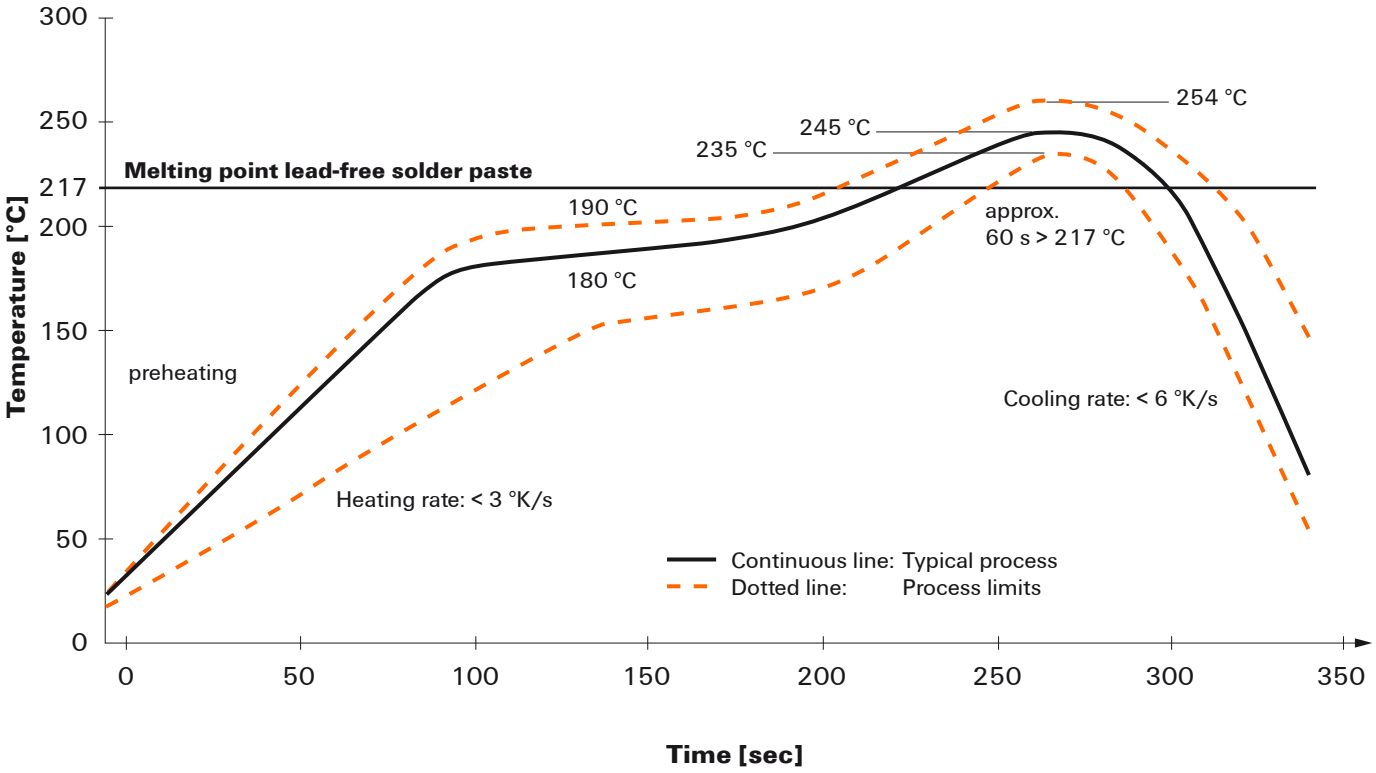
The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

We reserve the right to make technical changes.

Reflow Solder Profile

Recommended reflow soldering profile

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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:
- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically ≤ +3K/s. In parallel the solder paste is ‚activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at ≥ -6K/s solder is cured. Board and components cool down while avoiding cold cracks.

We reserve the right to make technical changes.